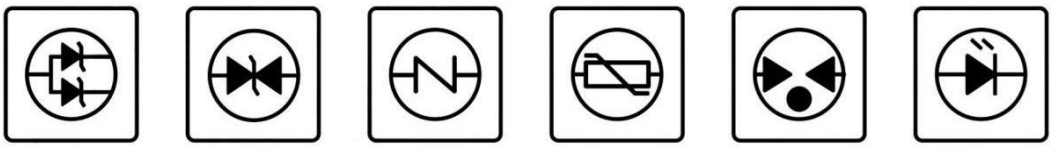
MSKSEMI 美森科
SEMICONDUCTOR



SS1045B THRU SS10200B

Product specification

SS1045B THRU SS10200B

VOLTAGE RANGE 45 to 200 Volts
CURRENT 10.0Ampere

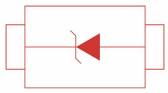
FEATURES

- Ideal for surface mount applications
- Easy pick and place
- Built-in strain relief
- Low forward voltage drop

MECHANICAL DATA

- Case: Molded plastic
- Epoxy: UL 94V-0 rate flame retardant
- Metallurgically bonded construction
- Polarity: Color band denotes cathode end
- Mounting position: Any
- Weight: 0.093 grams

Reference News

SMB	Schematic Diagram
	

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode

Marking

SS1045B	SS1060B	SS10100B	SS10150B	SS10200B
SS1045	SS1060	SS10100	SS10150	SS10200

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25℃ ambient temperature unless otherwise specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%

P/N(MARK)	SS1045B	SS1060B	SS10100B	SS10150B	SS10200B	UNITS
Maximum Recurrent Peak Reverse Voltage	45	60	100	150	200	V
Maximum RMS Voltage	32	42	70	105	140	V
Maximum DC Blocking Voltage	45	60	100	150	200	V
Maximum Average Forward Rectified Current See Fig. 1	10.0					A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	175					A
Maximum Instantaneous Forward Voltage at 10.0A	0.55	0.7	0.85	0.92		V
Maximum DC Reverse Current Ta=25℃	0.5					mA
at Rated DC Blocking Voltage Ta=100℃	50					mA
Typical Junction Capacitance (Note1)	400					pF
Typical Thermal Resistance R JA (Note 2)	16					℃/W
Operating Temperature Range TJ	—	-55 to +150			——	℃
Storage Temperature Range TSTG	-55 to +150					℃

NOTES:

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

2. Thermal Resistance Junction to Lead.

RATING AND CHARACTERISTIC CURVES (SS1045B THRU SS10200B)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

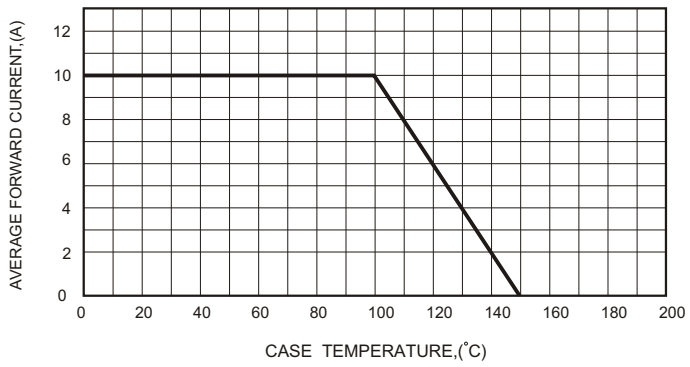


FIG.2-TYPICAL FORWARD CHARACTERISTICS

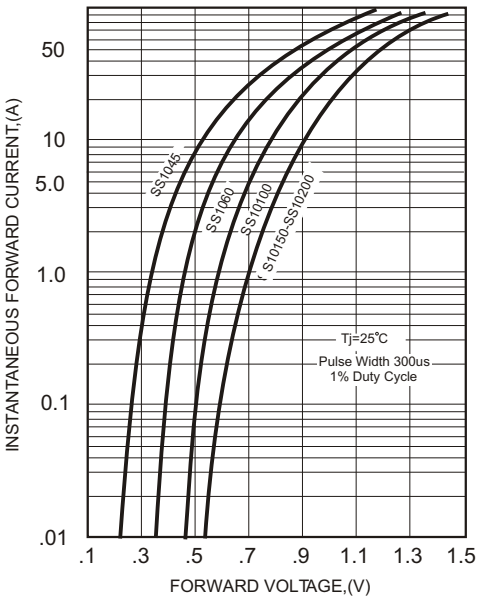


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

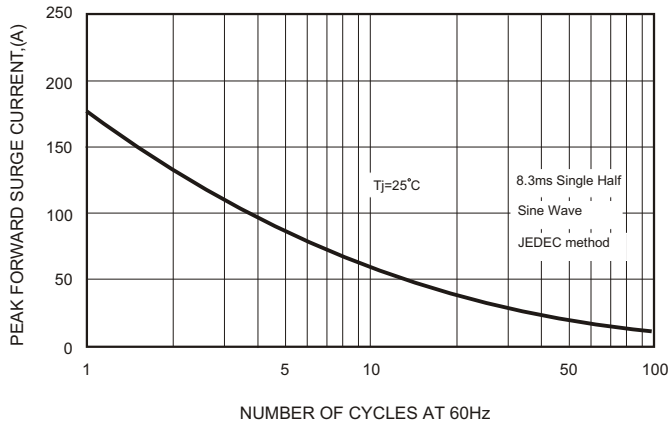


FIG.4-TYPICAL JUNCTION CAPACITANCE

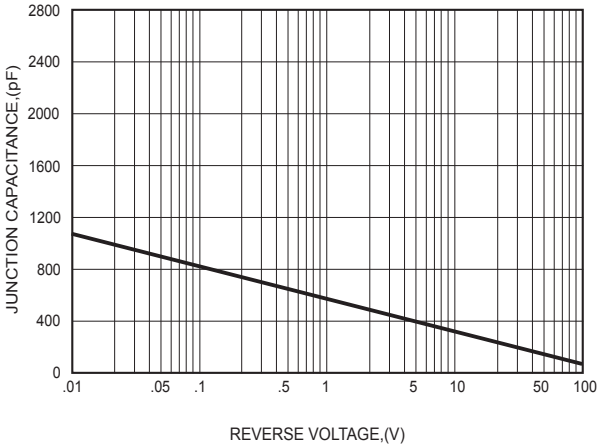
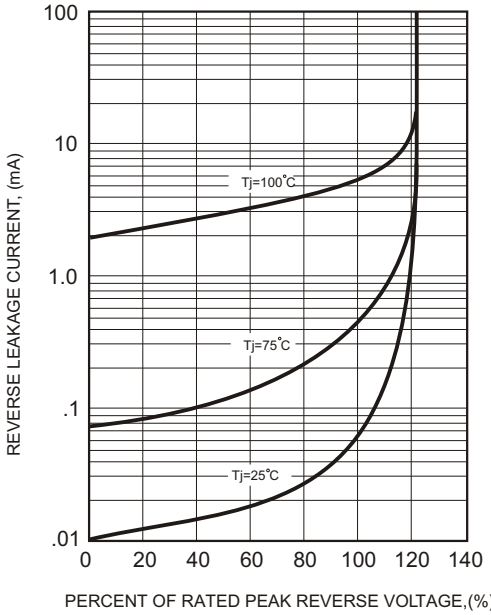
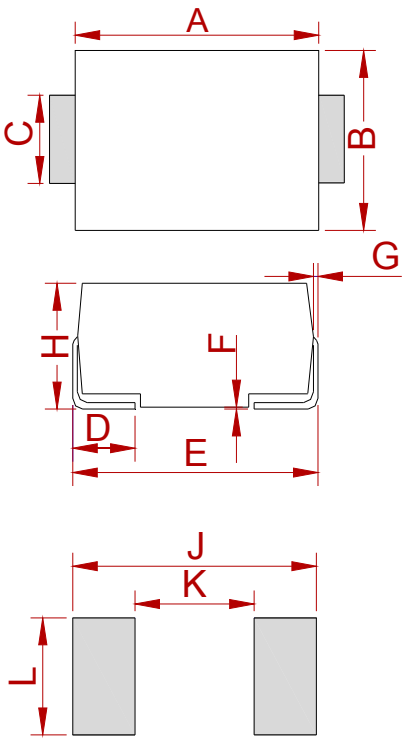


FIG.5 - TYPICAL REVERSE CHARACTERISTICS



PACKAGE MECHANICAL DATA



DO-214AA (SMB)

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.25	4.75	0.167	0.187
B	3.30	3.94	0.130	0.155
C	1.85	2.21	0.073	0.087
D	0.76	1.52	0.030	0.060
E	5.08	5.59	0.200	0.220
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	2.11	2.44	0.083	0.096
J	6.80		0.270	
K		2.60		0.100
L	2.40		0.090	

REEL SPECIFICATION

P/N	PKG	QTY
SS1045B THRU SS10200B	SMB	3000

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